



Product Change Notification: CENO-27LEFG478

Date:

01-May-2025

Product Category:

8-Bit Microcontrollers

Notification Subject:

CCB 7138.002 Final Notice: Qualification of QMI519 as a new die attach material for selected PIC18F56K42, PIC18F55K42, PIC18F57Q43, PIC18F56Q83, PIC18F56Q84, AVR32DA48, PIC18F57Q83, PIC18F57Q84, PIC18F56Q43, PIC18F54Q71, PIC18F55Q71, PIC18F56Q71, AVR128DA48, PIC16F15385, PIC16F15386, AVR64DB48, AVR32DB48, AVR128DB48, AVR64DA48, PIC16F19186, PIC16F19185, PIC18F55Q43, PIC18F55Q24, PIC18F56Q24 and PIC18F57K42 device families available in 48L TQFP (7x7x1mm) package at MTAI assembly site.

Affected CPNs:

[CENO-27LEFG478_Affected_CPN_05012025.pdf](#)

[CENO-27LEFG478_Affected_CPN_05012025.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of QMI519 as a new die attach material for selected PIC18F56K42, PIC18F55K42, PIC18F57Q43, PIC18F56Q83, PIC18F56Q84, AVR32DA48, PIC18F57Q83, PIC18F57Q84, PIC18F56Q43, PIC18F54Q71, PIC18F55Q71, PIC18F56Q71, AVR128DA48, PIC16F15385, PIC16F15386, AVR64DB48, AVR32DB48, AVR128DB48, AVR64DA48, PIC16F19186, PIC16F19185, PIC18F55Q43, PIC18F55Q24, PIC18F56Q24 and PIC18F57K42 device families available in 48L TQFP (7x7x1mm) package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change
--	------------	-------------

Assembly Site	Microchip Technology Thailand (HQ) (MTAI)		Microchip Technology Thailand (HQ) (MTAI)
Wire Material	Au	CuPdAu	CuPdAu
Die Attach Material	3280		QMI519
Molding Compound Material	G700HA		G700HA
Lead-Frame Material	C7025		C7025

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying QMI519 as a new die attach material.

Change Implementation Status: In Progress

Estimated First Ship Date: 23 June 2025 (date code: 2526)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	May 2025					June 2025				
Work Week	18	19	20	21	22	23	24	25	26	27
Qual Report Availability	x									
Final PCN Issue Date	x									
Estimated Implementation Date									x	

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_{PCN}_Qual_Report.

Revision History: May 1, 2025: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[**PCN_CENO-27LEFG478-Qual Report.pdf**](#)

Please contact your local [**Microchip sales office**](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [**PCN home page**](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [**PCN FAQ**](#) section.

If you wish to change your PCN profile, including opt out, please go to the [**PCN home page**](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.